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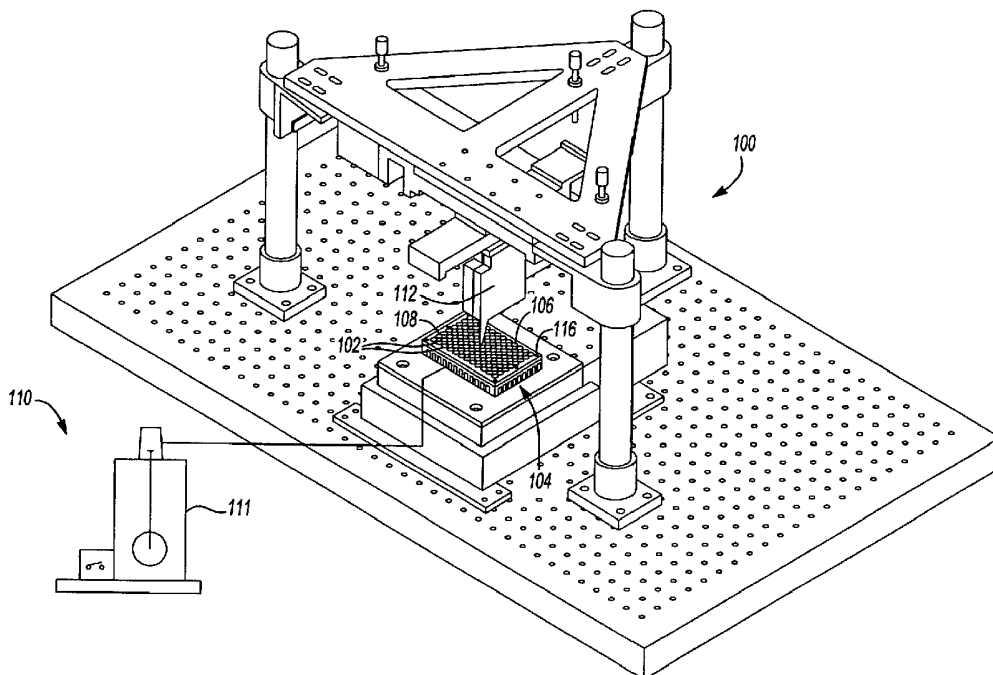
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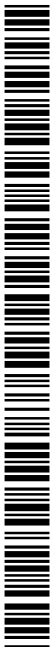
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[Continued on next page]

(54) Title: HIGH THROUGHPUT MECHANICAL PROPERTY TESTING OF MATERIALS LIBRARIES USING FLUID, VOLTAGE, AND PIEZOELECTRIC



(57) Abstract: A method for high throughput mechanical property testing of materials libraries. A suitable system, such as an automated system 10, is provided. A plurality of samples on a substrate are monitored for their response to a force directed by a Force Application source (FAS) 18, where the force applied is selected from the group consisting of a fluid, a voltage, a piezoelectric, and a combination thereof.



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